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[54] **SILICONE PRESSURE-SENSITIVE ADHESIVE COMPOSITION**

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[52] U.S. Cl. **525/478; 528/15; 528/31; 528/32**

[58] Field of Search **528/15, 31, 32; 525/478**

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[57] **ABSTRACT**

A pressure-sensitive adhesive having an excellent tack and adhesive strength is obtained from a composition which contains an alkenyl group-containing silicone polymer, a tackifying silicone resin having less than one percent hydroxyl content, an organohydrogen-polysiloxane curing agent for the alkenyl group-containing silicone polymer and a platinum-containing catalyst. The composition can be cured to a silicone pressure-sensitive adhesive by heating at relatively low temperatures.

9 Claims, No Drawings